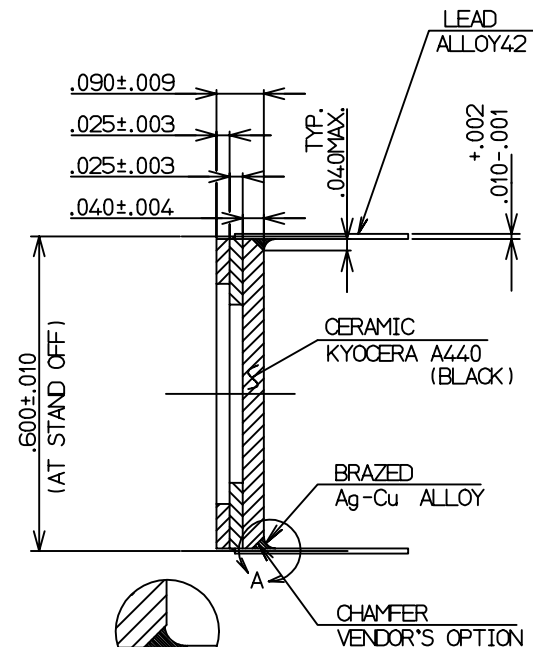
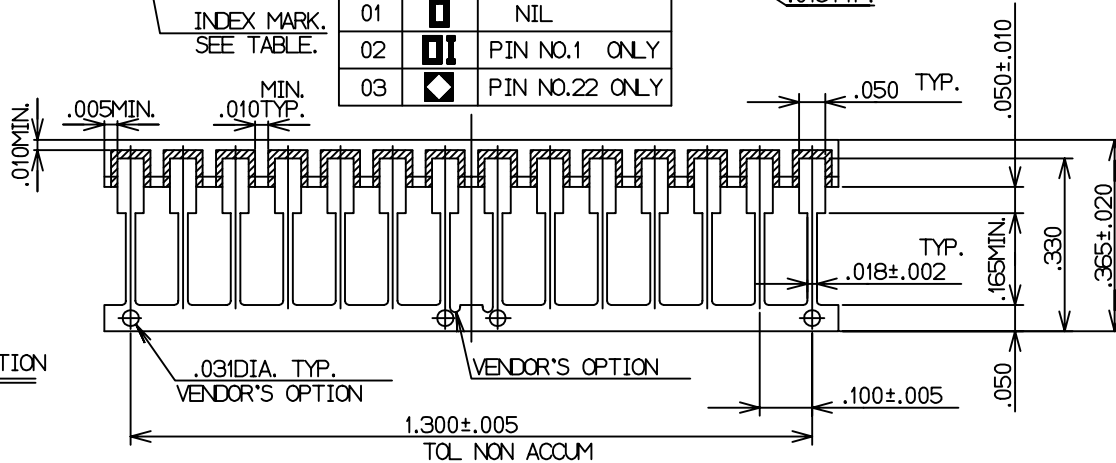


PART NO.	INDEX MARK	LEAD TIED DOWN
01	□	NIL
02	◻	PIN NO.1 ONLY
03	◼	PIN NO.22 ONLY

INDEX MARK. SEE TABLE.



DETAIL-A

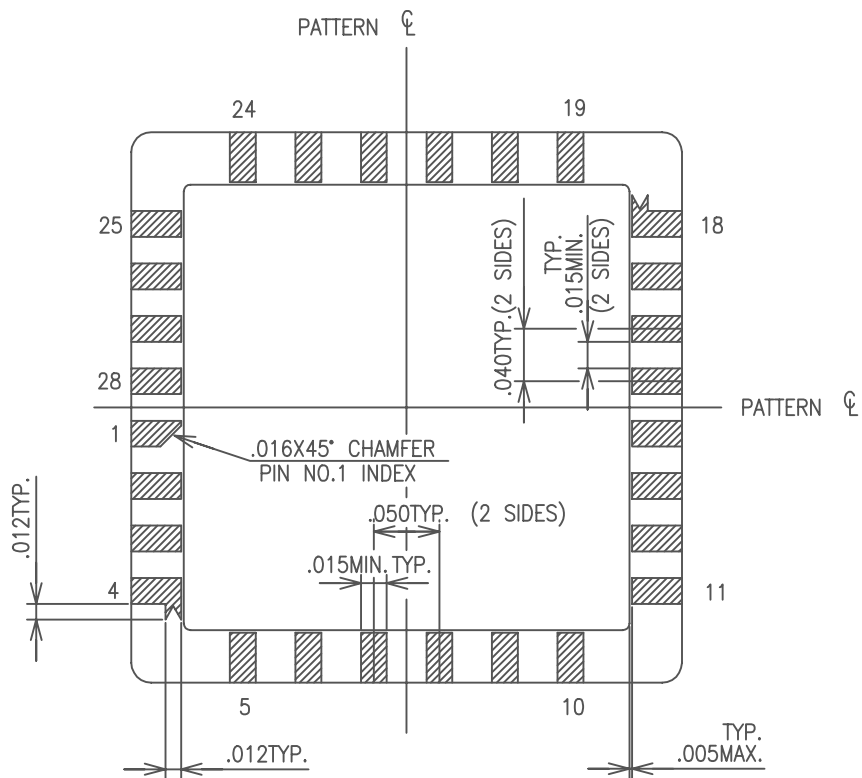
NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. LEAD RESISTANCE : 0.30Ω MAX.

S8028K423-3	S=0 D=22
S8028K423-2	S=0 D=1
S8028K423-1	S=0 D=0

MODIFICATION	DATE	DRAWN	CHECKED	APPROVED
REDRAWN (CONVERTED CAD DATA) CHANGED	SEP.02'98	H.SH	H.SU S.F	T.A

NAME 28 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION	DRAWN T.H	CHECKED K.M	APPROVED	DATE SEP.02.'98
SCALE 4/1	MATERIAL AS INDICATED	DRAWING NO. KD-80423-E		SHEET 1/2	
		KYOCERA CORPORATION KYOTO JAPAN			



BONDING PATTERN

MODIFICATION	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED	NAME	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
								T.H	K.M		SEP.02.'80
						28 LEAD SIDE BRAZED PACKAGE					
						SCALE 10 / 1					
						MATERIAL					
							THIRD ANGLE PROJECTION				
△	REDRAWN (CONVERTED CAD DATA) CHANGED	SEP.02.'93	H.SH	H.SU S.F	T.A						
		DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-80423-E		SHEET 2 / 2	